



Description

JMG N-channel Advanced Mode Power MOSFET

Features

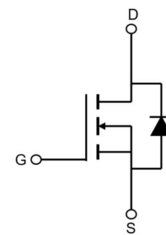
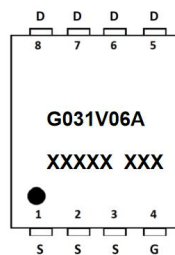
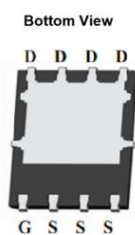
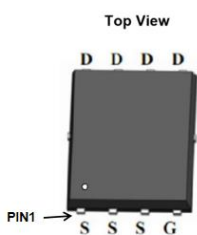
- 60V,160A
 $R_{DS(ON)} < 3m\Omega @ V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Application

- Load Switch
- PWM Application
- Power Management



100% UIS TESTED!
100% ΔV_{ds} TESTED!



PDFN5x6-8L

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

| Device Marking | Device | Outline | Package | Reel Size | Reel (pcs) | Per Carton (pcs) |
|----------------|-------------|---------|------------|-----------|------------|------------------|
| G031V06A | JMGG031V06A | TAPING | PDFN5x6-8L | 13" | 5000 | 50000 |

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

| Symbol | Parameter | Max. | Units |
|-----------------|---|---------------------|--------------|
| V_{DSS} | Drain-Source Voltage | 60 | V |
| V_{GSS} | Gate-Source Voltage | ± 25 | V |
| I_D | Continuous Drain Current | $T_C = 25^\circ C$ | 160 |
| | | $T_C = 100^\circ C$ | 104 |
| I_{DM} | Pulsed Drain Current ^{note1} | 640 | A |
| E_{AS} | Single Pulsed Avalanche Energy ^{note2} | 196 | mJ |
| P_D | Power Dissipation | $T_C = 25^\circ C$ | 125 |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 1 | $^\circ C/W$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ C$ |



Electrical Characteristics (T_J=25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|---|--|------|------|------|-------|
| Off Characteristics | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 60 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =60V, V _{GS} =0V, | - | - | 1.0 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±25V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 2 | 3 | 4 | V |
| R _{DS(on)} | Static Drain-Source on-Resistance <small>note3</small> | V _{GS} =10V, I _D =30A | - | 2.3 | 3.0 | mΩ |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, f=1.0MHz | - | 3383 | - | pF |
| C _{oss} | Output Capacitance | | - | 1940 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 14 | - | pF |
| Q _g | Total Gate Charge | V _{DD} =30V, I _D =40A, V _{GS} =10V | - | 46 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 17 | - | nC |
| Q _{gd} | Gate-Drain("Miller") Charge | | - | 10 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DD} =30V, I _D =40A, R _{GEN} =2.7Ω, V _{GS} =10V | - | 19 | - | ns |
| t _r | Turn-on Rise Time | | - | 105 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 35 | - | ns |
| t _f | Turn-off Fall Time | | - | 107 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 160 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 640 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S =30A | - | - | 1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | V _{DS} =60V, I _F =40A, di/dt=300A/μs | - | 50 | - | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | | - | 115 | - | nC |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: Starting T_J=25°C, V_{DD}=30V, V_G=10V, R_G=25Ω, L=0.5mH, I_{AS}=28A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure 1: Output Characteristics

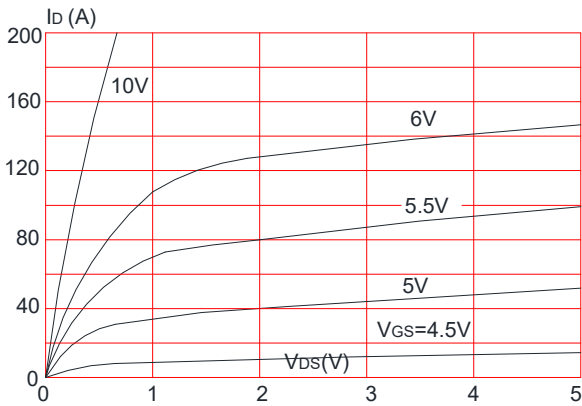


Figure 2: Typical Transfer Characteristics

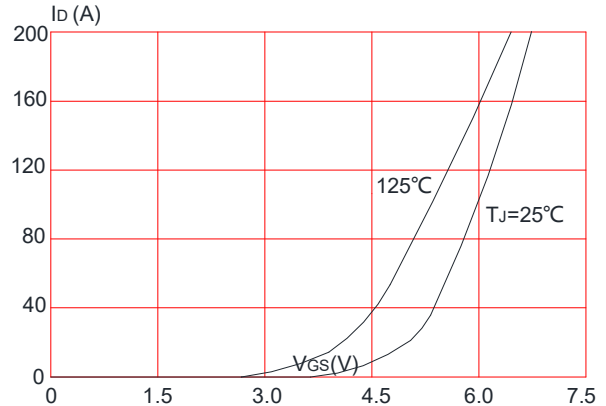


Figure 3: On-resistance vs. Drain Current

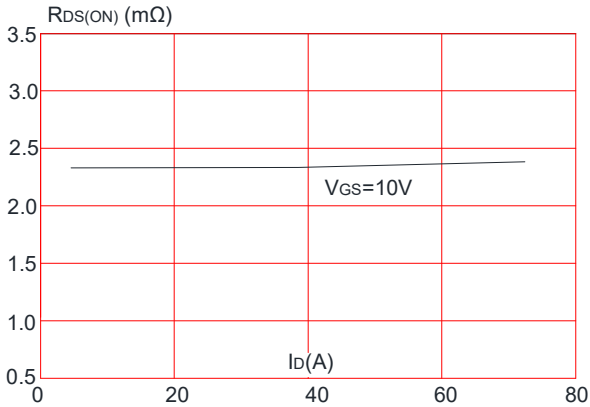


Figure 4: Body Diode Characteristics

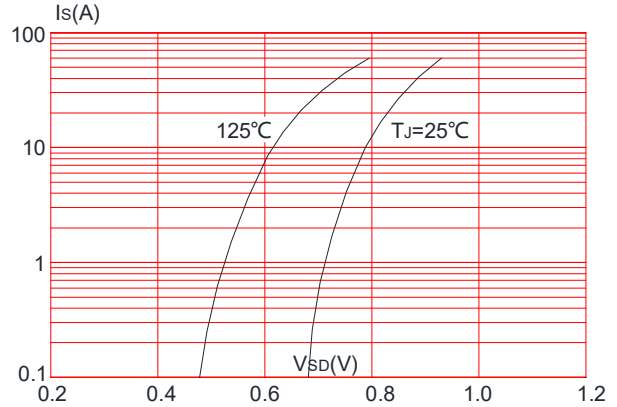


Figure 5: Gate Charge Characteristics

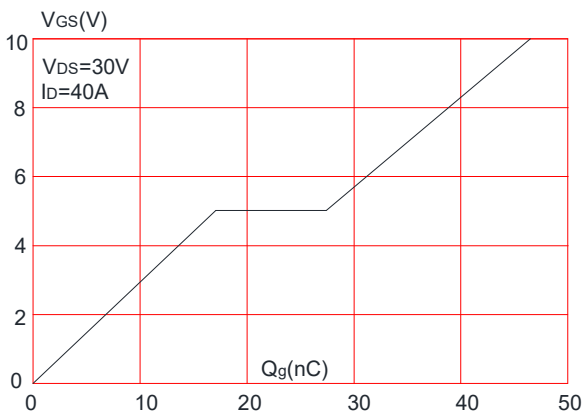


Figure 6: Capacitance Characteristics

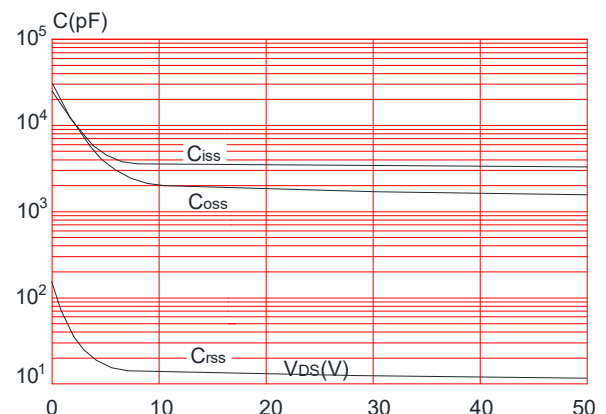




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

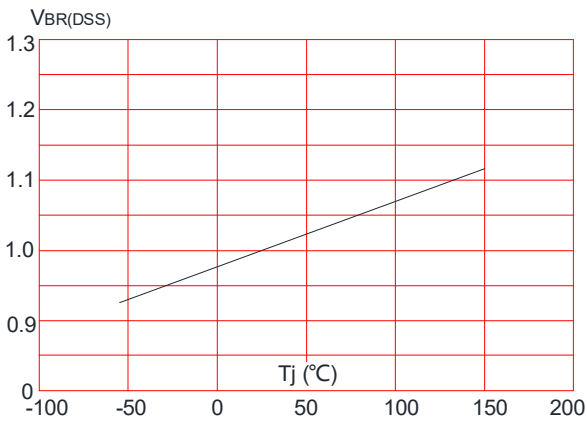


Figure 8: Normalized on Resistance vs. Junction Temperature

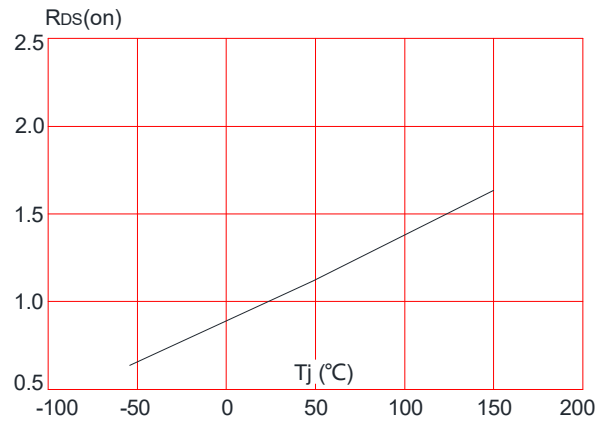


Figure 9: Maximum Safe Operating Area

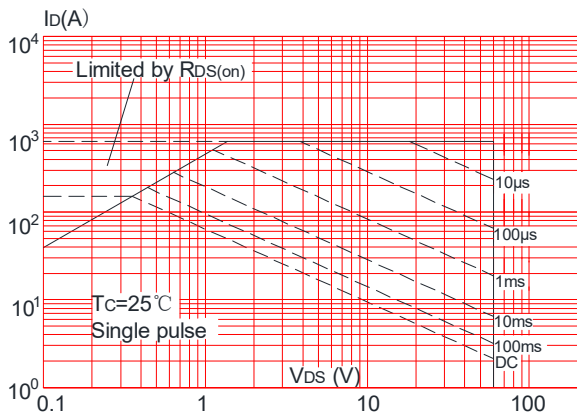


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

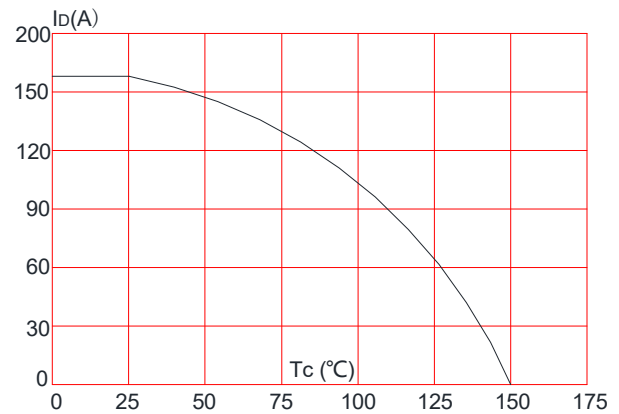
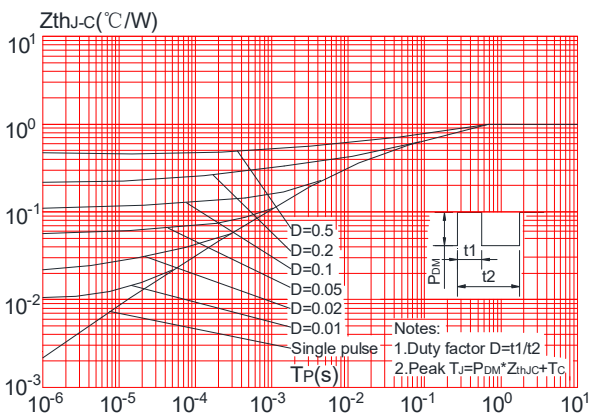


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Test Circuit

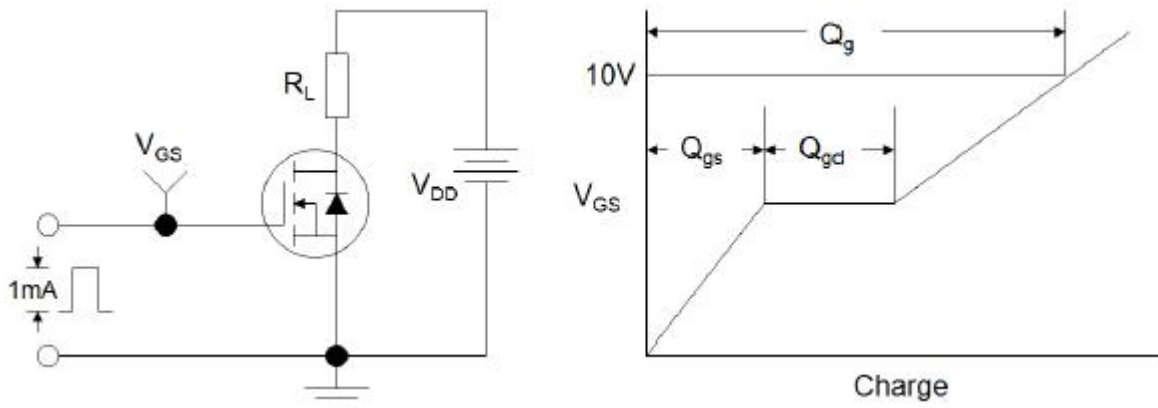


Figure1:Gate Charge Test Circuit & Waveform

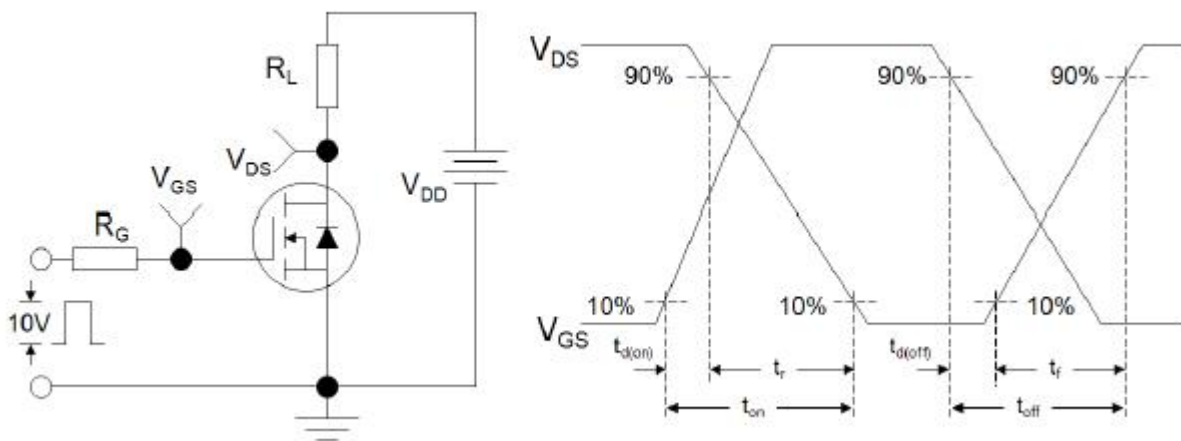


Figure 2: Resistive Switching Test Circuit & Waveforms

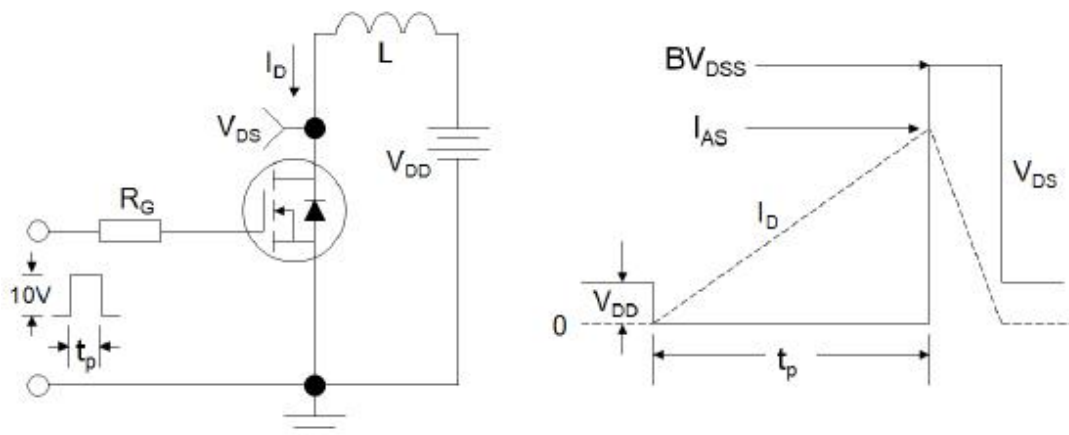
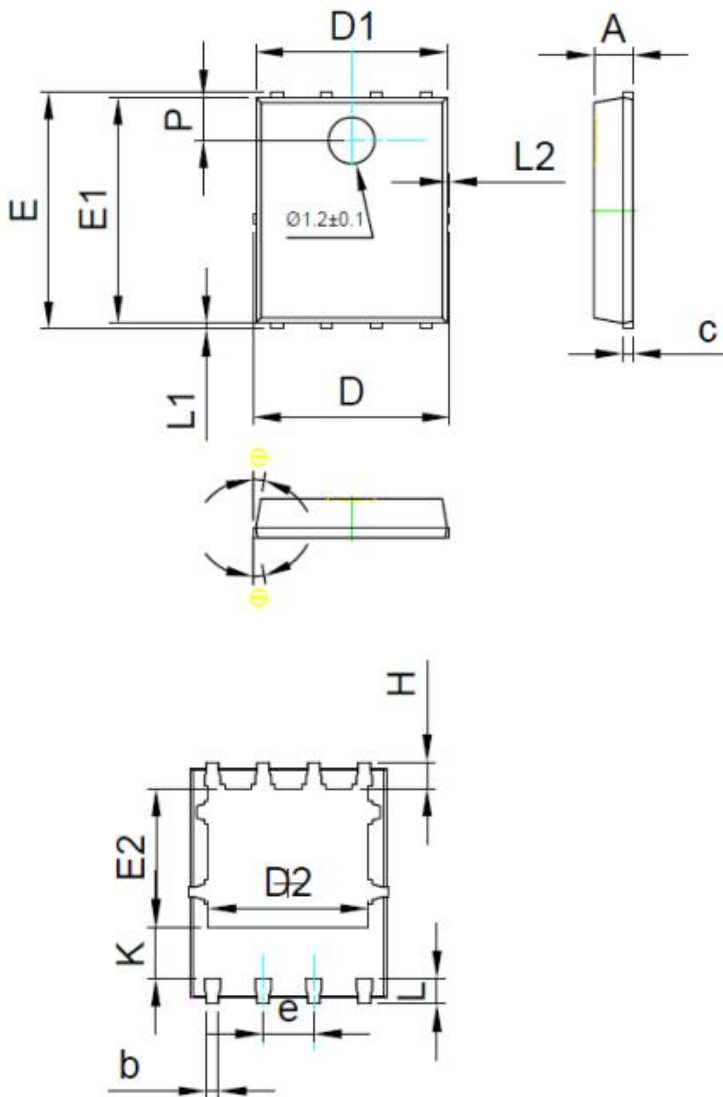


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data-PDFN5x6-8L



| SYMBOL | MIN | NOM | MAX |
|--------|----------|-------|-------|
| A | 0.90 | 1.00 | 1.10 |
| b | 0.35 | 0.40 | 0.45 |
| c | 0.21 | 0.25 | 0.34 |
| D | - | - | 5.10 |
| D1 | 4.85 | 4.90 | 4.95 |
| D2 | 3.96 | 4.01 | 4.06 |
| e | 1.27 BSC | | |
| E | 5.95 | 6.00 | 6.05 |
| E1 | 5.70 | 5.75 | 5.80 |
| E2 | 3.425 | 3.475 | 3.525 |
| H | 0.60 | 0.65 | 0.70 |
| K | 1.29 | - | - |
| L | 0.60 | 0.65 | 0.70 |
| L1 | 0.05 | 0.15 | 0.25 |
| L2 | - | - | 0.12 |
| ⊖ | 8° | 10° | 12° |
| P | 1.05 | 1.10 | 1.15 |

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